

## METHOD AND APPARATUS FOR SHOCK AND VIBRATION ISOLATION OF A CIRCUIT COMPONENT

### ABSTRACT OF THE DISCLOSURE

An apparatus for improved shock and vibration isolation of a CGA integrated package which utilizes solder column grid arrays to provide electrical connection to a printed circuit board. The CGA integrated package includes a substrate and a package lid. A support frame is attached at an attachment point to the substrate or the package lid of the CGA integrated package and at a second attachment point to the printed circuit board. An isolation material, such as Styrofoam or Sorbathane is located at the attachment point of the support frame to the substrate or the package lid, or located at the second attachment point of the support frame to the circuit board such that a vibration or shock to the circuit board must travel through the isolation material at the attachment point prior to reaching the integrated circuit. A method of supporting an integrated circuit on a circuit board and improving the isolation of an integrated circuit from any vibration and shock to the circuit board is also provided.